# Investor Presentation

Bank of America TMT Conference

June 12, 2024

# Disclaimer

This presentation contains forward-looking statements relating to the business, financial performance and earnings of SÜSS MicroTec SE and its subsidiaries and associates.

Forward-looking statements are based on current plans, estimates, projections and expectations and are therefore subject to risks and uncertainties, most of which are difficult to estimate and which in general are beyond the control of SÜSS MicroTec SE. Consequently, actual developments as well as actual earnings and performance may differ materially from those which explicitly or implicitly assumed in the forward-looking statements.

SÜSS MicroTec SE does not intend or accept any obligation to publish updates of these forward-looking statements.

SUSS is part of our digital life!



# SUSS MicroTec at a glance

- Hidden champion headquartered in Germany with 75 years track record of innovation and growth
- Key technology provider for semiconductor frontend and advanced backend industry
- Global customer base with largest share of business in Asia
- Strategic partner for global semiconductor IDMs and foundries
- Innovator with relevant network to research institutes and universities
- 2025 Target: € 400 million revenue and >15% EBIT margin

| 304.3 in € million | 420.5 in € million | 9.1% |
|---|---|---|
| Sales 2023 | Order intake 2023 | EBIT margin 2023 |

# Management Board of SÜSS MicroTec SE

CFO

## Dr. Cornelia Ballwiesser

- Finance and Controlling
- Legal and Compliance
- Internal Audit
- Investor Relations
- IT
- ESG

CEO

## Burkhardt Frick

- Sales and Service
- Strategy
- HR
- Business Units:
  Advanced Backend Solutions,
  Photomask Solutions

COO

## Dr. Thomas Rohe

- R&D
- Purchasing
- Production
- Logistics
- Quality Management
- Product Center
- Facility Management

# Our corporate vision defines our strategies

SUSS MicroTec Vision

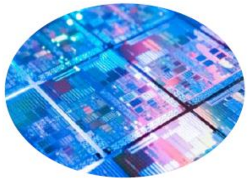
## **Leader in enabling innovative advanced backend & photomask solutions.**

# Our world are the semiconductor frontend and backend process steps

## Wafer fabrication

## Front-end-of-line

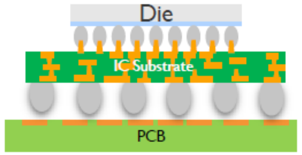
Wafer process



- Deposition/coating
- Cleaning
- **Patterning/lithography**[1]
- Etching
- Implantation
- Annealing
- **Permanent bonding**
- **Temporary bonding**
- CMP polishing

## From middle-of-line to back-end-of-line

Advanced packaging




- Deposition/coating
- Cleaning
- **Patterning/lithography**
- Etching
- Annealing
- CMP polishing
- **Permanent bonding**
- **Temporary bonding**
- **Wafer-level packaging**
- Wafer dicing
- Panel-level packaging

## Final packaging

- Mounting
- Wire bonding
- Molding encapsulation
- Trim & forming

[1] Only related to Photomask processing
Source: Yole, Lithography and Bonding Equipment for More than Moore 2022

# Advanced Backend Solutions is the core asset in our product portfolio

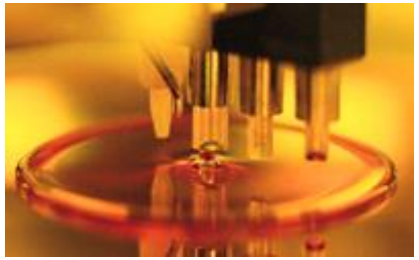
## Frontend

## Advanced Backend

**Segments**

Photomask Solutions

Advanced Backend Solutions



**Products**

### Photomask Equipment

MaskTrack X

### Imaging

Mask Aligner MA200/300

Projection Scanner DSC300

### Coating

ACS300

### Bonding

XBC300

XB8

# Focus on high-volume manufacturing markets while semi-automated tools will be phased-out during next years in Advanced Backend Solutions business unit

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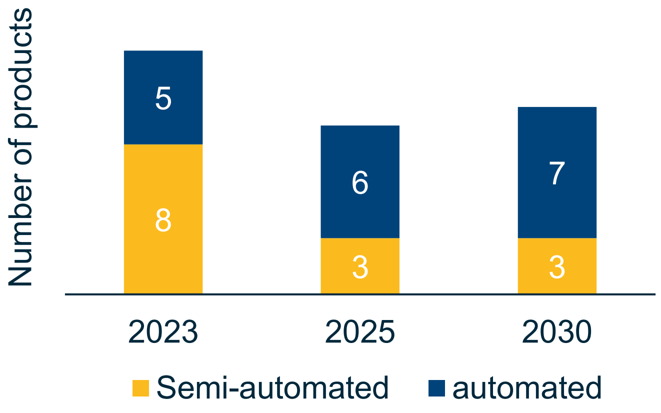
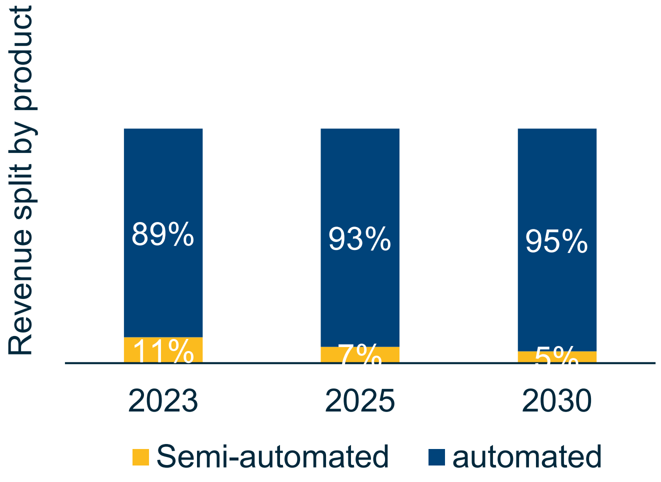
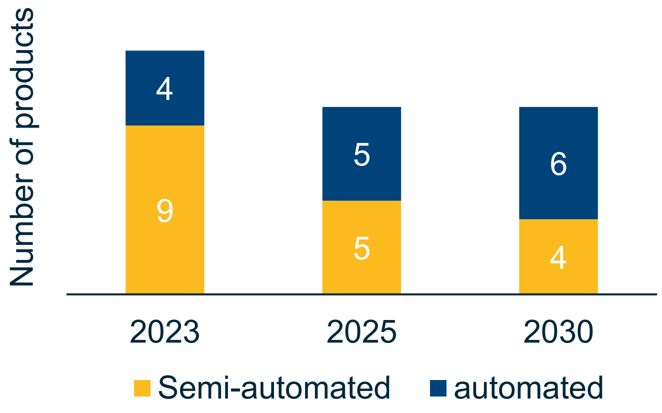
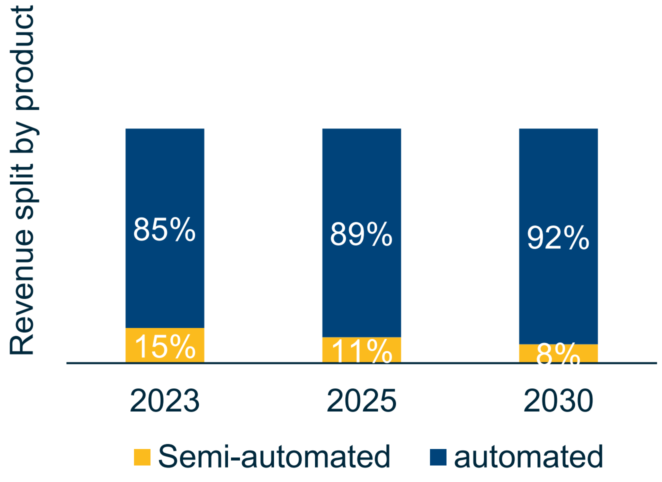
## Bonding Systems



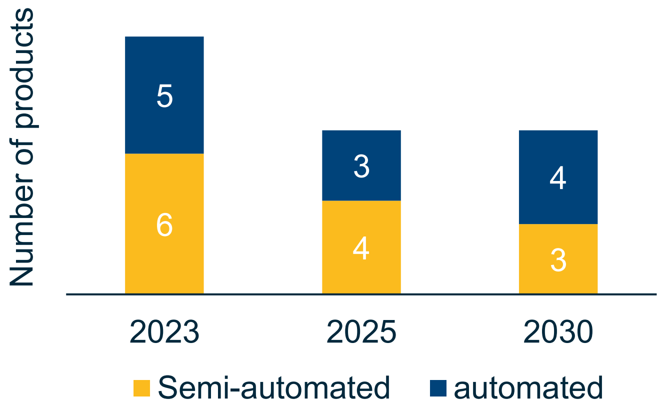



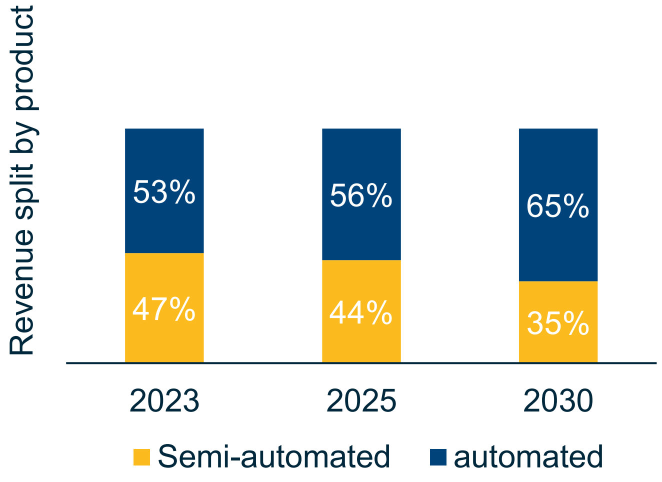

## Coating Systems




## Imaging Systems



# Full range of bonding solutions by SUSS

Bonding

## Temporary Bonding

**Temporary Bonding**
**XBS300**

**De-bonding / Cleaning**
**XBC300 Gen2**

**Mech. De-bonding (semi-auto)**
**DB12T**

## Permanent Bonding

**Bonding (200mm)**
**XBS200**

**High-force Bonding (semi-auto)**
**SB8 Gen2 /XB8**

## Hybrid Bonding

**W2 (up to 200mm)**
**XBS200**

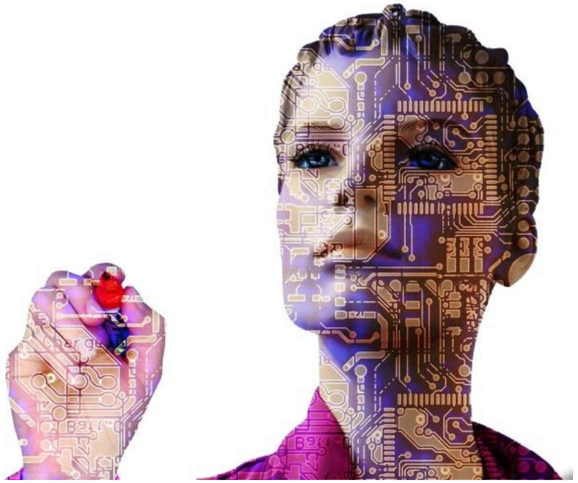
**W2W (up to 300mm)**
**XBS300 W2W**

**D2W & W2W**
**XBC300 Gen2 D2W/W2W**

**D2W**
**XBC300 Gen2 D2W**

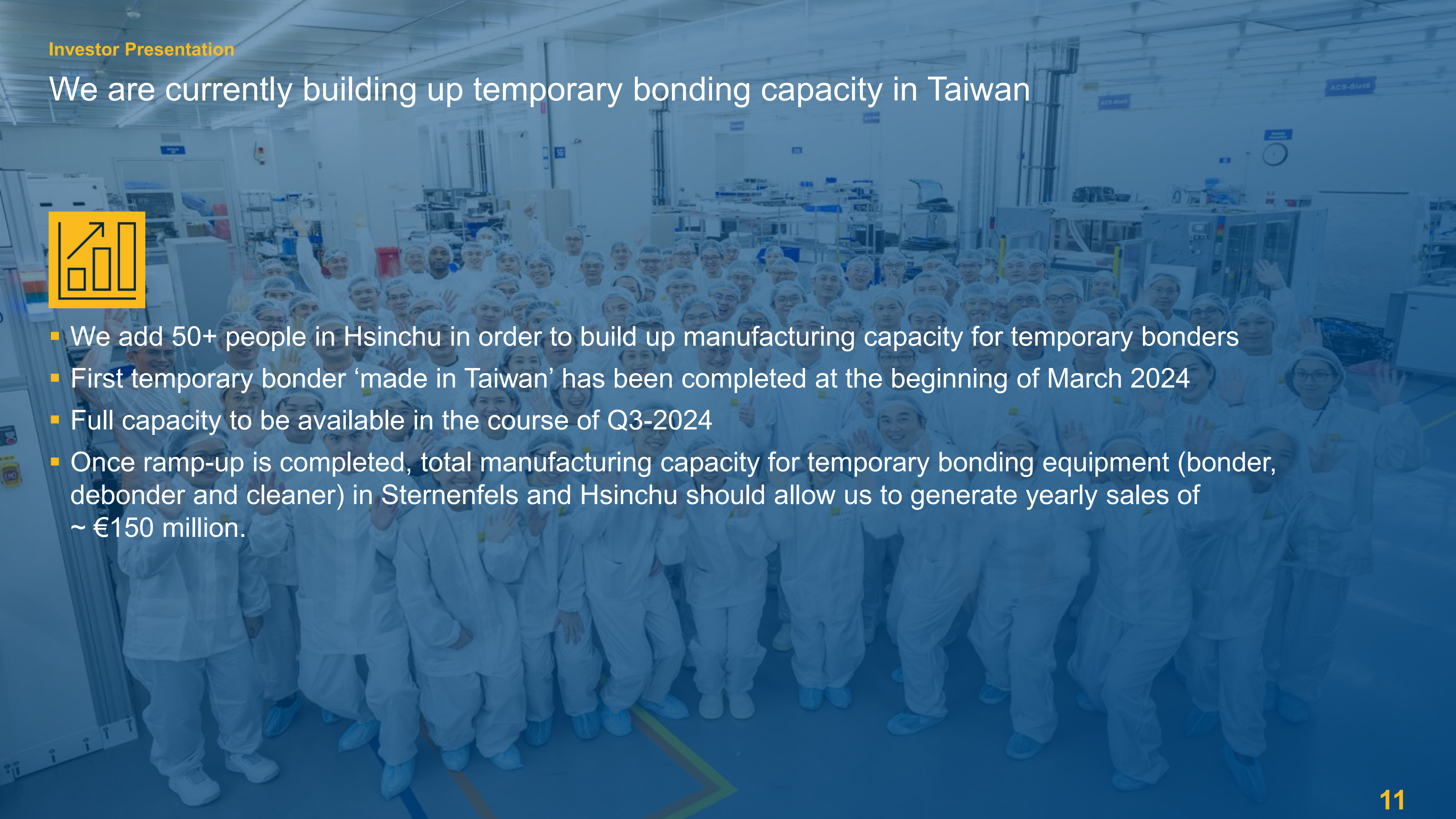
# AI related opportunity is larger than we initially expected

**So far, we received AI related orders for our temporary bonders, debonders and cleaners worth ~ € 200 million.**



- Demand for our solutions is boosted in particular by dramatic capacity increase at Korean and Taiwanese HBM (high bandwidth memory chip) manufacturers.
- After a first order in June 2023, we continuously received further orders
- As a result, order intake and sales for bonders went up considerably
- To meet demand, we are qualifying our production site in Hsinchu (Taiwan) to build the XBS300 temporary bonding platform in the future. For this, we are hiring > 50 new employees.

# We are currently building up temporary bonding capacity in Taiwan



- We add 50+ people in Hsinchu in order to build up manufacturing capacity for temporary bonders
- First temporary bonder ‘made in Taiwan’ has been completed at the beginning of March 2024
- Full capacity to be available in the course of Q3-2024
- Once ramp-up is completed, total manufacturing capacity for temporary bonding equipment (bonder, debonder and cleaner) in Sternenfels and Hsinchu should allow us to generate yearly sales of ~ €150 million.

# We benefit from the boom in AI, especially by supporting HBM manufacturing

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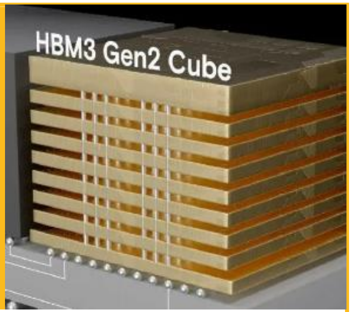
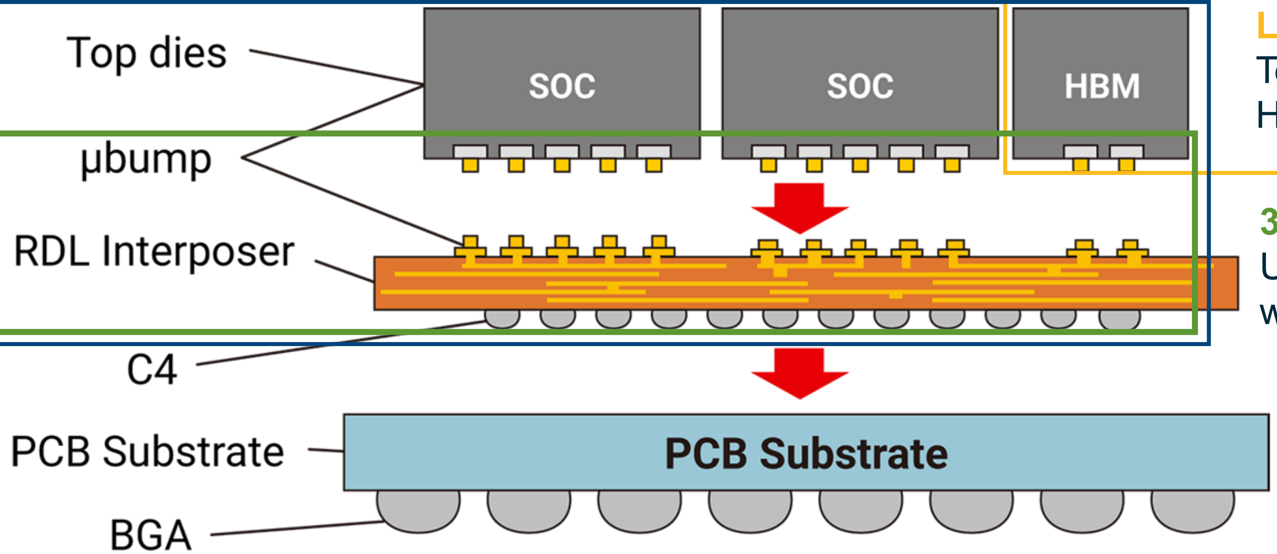



**Largest opportunity:**
Temporary bonding for HBM manufacturers

## CoWoS process

**2nd opportunity:**
Temporary bonding for pressure annealing of interposer




**3rd opportunity:**
UV Projection Scanner for rougher wiring of µbumps and interposer

Sources: TSMC, Micron

CoWoS – chip on wafer on substrate
SOC – system on chip
HBM – high bandwidth memory
RDL – redistribution layer
C4 – controlled collapse chip connection
PCB – printed circuit board
BGA – ball grid array

# SUSS hybrid bonding solutions – understanding customer's needs

**Wafer-to-wafer HB**
XBS300 W2W

Product launch: 10/2022
Target customers: HVM

**Die-to-wafer/wafer-to-wafer HB**
XBC300 Gen2 D2W/W2W

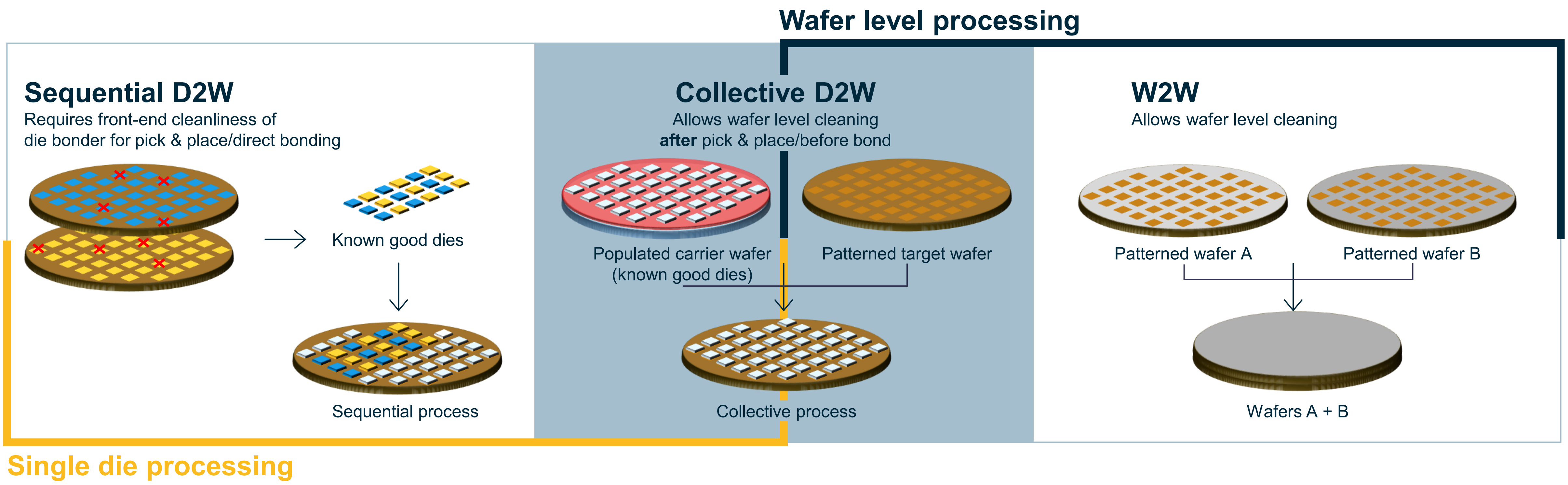
Product launch: 05/2024
Target customers: research institutes, R&D teams of HVM

**Die-to-wafer HB**
XBC300 Gen2 D2W

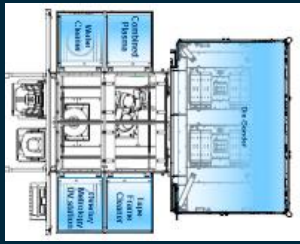
Product launch: Q4/2024
Target customers: HVM

**We optimize our product solutions to serve our customer's device and manufacturing needs.**

# SUSS MicroTec's solutions for different hybrid bonding processing schemes

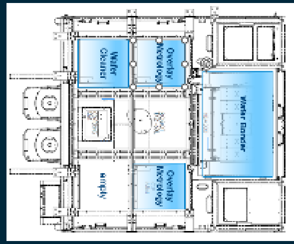



## Surface Preparation (SP) & D2W

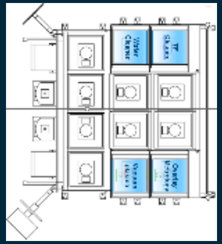


## SP & D2W/W2W

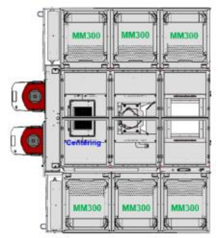
## SP & W2W



## SP only



## Overlay only



# Record for order intake and sales, while margins need improvement

## Financial Results
FY 2023*

| 420.5 | 304.3 | 34.1 | 9.1 |
|---|---|---|---|
| in € million | in € million | in % | in % |
| Order intake<br>FY 2023 | Sales<br>FY 2023 | Gross profit margin<br>FY 2023 | EBIT margin<br>FY 2023 |

*excluding divested MicroOptics business

# Division Overview FY 2023

SÜSS MicroTec

## Advanced Backend Solutions

| in € million | FY 2023 | FY 2022 |
|---|---|---|
| **Order intake** | 296.4 | 279.7 |
| - thereof Lithography | 139.6 | 203.0 |
| - thereof Bonder | 156.8 | 76.6 |
| **Total sales**[1] | 214.7 | 210.9 |
| - thereof Lithography | 163.0 | 175.8 |
| - thereof Bonder | 51.7 | 35.0 |
| **Gross profit** | 77.8 | 82.4 |
| **Gross profit margin** | 36.2% | 39.1% |
| **EBIT** | 20.1 | 28.5 |
| **EBIT margin** | 9.3% | 13.5% |

- Further increase in order intake yoy driven by multiple orders in the bonding segment, especially for temporary bonding equipment for AI-applications
- Sales increased yoy, driven by bonder business, which more than compensated for the rather weak lithography sales in 2023
- Gross profit margin decreased because of a disproportionately increase in cost of sales and an unfavorable product mix
- EBIT margin decreased from 13.5% to 9.3% (EBIT 2022 includes a positive one-off effect of € 0.8 million)

## Photomask Solutions

| in € million | FY 2023 | FY 2022 |
|---|---|---|
| **Order intake** | 124.1 | 130.9 |
| **Total sales**[1] | 89.7 | 48.8 |
| **Gross profit** | 26.5 | 16.8 |
| **Gross profit margin** | 29.6% | 34.4% |
| **EBIT** | 12.4 | 6.1 |
| **EBIT margin** | 13.8% | 12.5% |

- Order intake decreased slightly, but remains on a very good level compared to prior years
- High order book (~ €166 million as of December 31, 2023) provides further growth opportunity
- Sales benefited from high order book and improved supply chain situation
- Absolute gross profit and EBIT improved strongly
- Decline in gross profit margin due to additional costs incurred for the ongoing onboarding of new external production partners

1) Total sales include internal sales (sales to other divisions); gross profit margin and EBIT margin are calculated on the basis of total sales.

# We want to grow further and increase profitability at the same time

## Guidance 2024

Sales

**340-370**

**in € million**

Actual 2023:
**€ 304.3 million**

Gross profit margin

**35-38**

**in %**

Actual 2023:
**34.1%**

EBIT Margin

**10-12**

**in %**

Actual 2023:
**9.1 %**

# Record Q1 regarding sales, combined with strong margins

## Financial Results
## Q1 2024*

| 98.3 in € million | 93.5 in € million | 39.1 in % | 15.9 in % |
|---|---|---|---|
| Order intake Q1 2024 | Sales Q1 2024 | Gross profit margin Q1 2024 | EBIT margin Q1 2024 |

*excluding divested MicroOptics business

# Key CEO messages

- Strong first quarter regarding all key financial indicators
- Q1 sales exceeded market expectations, even if there is no substantial reason for seasonality at SUSS
- Order book reaches all time high at € 456.9 million and remains basis for further growth
- Gross profit margin and EBIT margin were strong due to a favorable product mix and the overall high sales volume
- Our main focus is to maintain this positive momentum in the coming months and quarters

→ We are on track to achieve our 2024 targets, but we are still in a growth-driven transformation process

# Division Highlights Q1 2024

## Strong execution in both divisions

**Advanced Backend Solutions:**

- Continued order intake for temporary bonding equipment, mainly supporting AI-driven HBM capacity ramp-up
- Two new customers for temporary bonding, thereof one customer for SiC; customer order for a 200mm wafer-to-wafer hybrid bonder received
- Based on strong order book, Bonding sales more than doubled in Q1 2024 vs. Q1 2023
- Order intake and sales for Imaging and Coating systems again rather weak in Q1 2024

**Photomask Solutions:**

- Good order intake with better momentum than in Q3 and Q4 2023
- Significant qoq sales increase of 60.6%, based on an ongoing well-filled order book and due to revenue recognition of two tools which already have been produced and shipped in Q4 2023

# Record Q1 regarding sales, combined with strong margins

| In € million | Q1 2024 | Q1 2023 | Change |
|---|---|---|---|
| **Order intake** | 98.3 | 94.9 | 3.6% |
| **Order book as of March 31** | 456.9 | 364.0 | 25.5% |
| **Sales** | 93.5 | 64.0 | 46.1% |
| **Gross profit** | 36.6 | 22.0 | 66.4% |
| **Gross profit margin** | 39.1% | 34.4% | 4.7%pts |
| **EBIT** | 14.9 | 3.8 | 292.1% |
| **EBIT margin** | 15.9% | 5.9% | 10.0%pts |
| **Earnings after taxes (continuing operations)** | 10.4 | 3.0 | 246.7% |
| **Net profit*** | 68.7 | 2.1 | - |
| **Earnings per share, basic (in €) continuing operations** | 0.54 | 0.16 | 237.5% |
| **Earnings per share, basic (in €)*** | 3.59 | 0.11 | - |
| **Net cash** | 102.4 | 42.5 | 140.9% |
| **Free cash flow (continuing operations)** | -3.9 | -1.2 | - |
| **Free cash flow total*** | 70.7 | 0.3 | - |
| **Employees as of March 31** | 1,273 | 1,094 | 16.4% |

*including divested MicroOptics business

SÜSS MicroTec

- Ongoing good order intake and record order book remain a solid foundation for growth in 2024 and beyond
- Gross profit and EBIT increased strongly, mainly because of a favorable product mix, the overall higher sales level and efficiency gains in the production, despite ongoing transformation efforts
- Gross profit margin and EBIT margin improved, supported by the higher gross profit
- Net profit includes extraordinary income from MicroOptics sale (€ 58.3 million)
- Net cash position significantly improved because of the sale of our MicroOptics business
- Number of employees has grown by ~180 people since end of Q1 2023

# Division Overview Q1 2024

SÜSS MicroTec

## Advanced Backend Solutions

| in € million | Q1 2024 | Q1 2023 |
|---|---|---|
| **Order intake** | 64.6 | 56.2 |
| **Sales** | 56.4 | 41.0 |
| **Order book** | 294.8 | 217.0 |
| **Gross profit** | 25.1 | 14.9 |
| **Gross profit margin** | 44.5% | 36.3% |
| **EBIT** | 7.2 | 0.7 |
| **EBIT margin** | 12.8% | 1.7% |

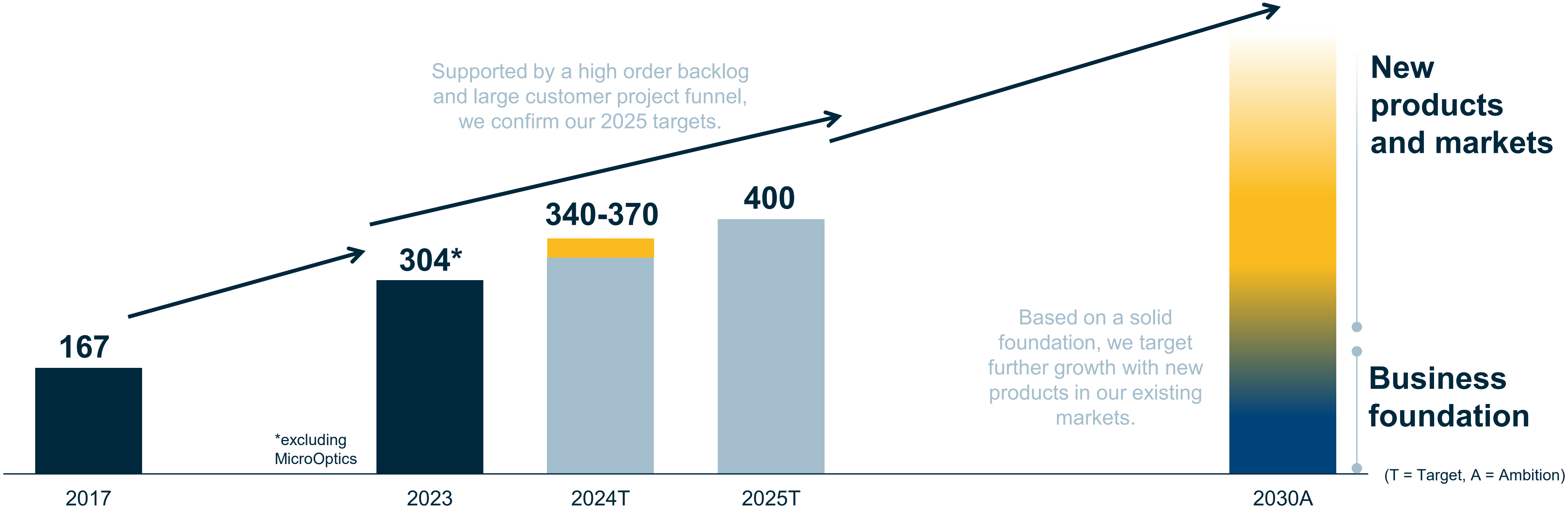
- Increase in order intake qoq, driven by ongoing good orders in the bonder product line, especially for temporary bonding equipment
- Order intake for a 200mm wafer-to-wafer hybrid bonder received in Q1
- Sales increased qoq, driven by bonder business, which again more than compensated for the rather challenging lithography sales in Q1 2024
- Gross profit margin increased due to higher sales volume, a favorable product mix and production efficiency gains in one product line
- EBIT margin increased accordingly from 1.7% to 12.8%

## Photomask Solutions

| in € million | Q1 2024 | Q1 2023 |
|---|---|---|
| **Order intake** | 33.7 | 38.6 |
| **Sales** | 37.1 | 23.1 |
| **Order book** | 162.1 | 147.0 |
| **Gross profit** | 12.2 | 7.0 |
| **Gross profit margin** | 32.9% | 30.3% |
| **EBIT** | 8.2 | 3.7 |
| **EBIT margin** | 22.1% | 16.0% |

- Order intake decreased slightly, but remains on a very good level compared to the previous quarters
- Sales benefited from execution of strong order book (still at high ~ €162 million as of March 31, 2024)
- Absolute gross profit and EBIT improved strongly as did the gross profit margin and the EBIT margin
- Further quarterly gross profit margin volatility cannot be excluded due to onboarding and collaborating with external manufacturing partners

# Based on our business foundation we see further potential beyond




## Major growth drivers 2023

- Converting high order backlog in Photomask Solutions and Bonder business into sales growth

## Major growth drivers 2024/2025

- Bonding (especially with regard to AI-driven demand for temporary bonders)
- Photomask Solutions

## Major growth drivers 2030

- General expected market growth in our core businesses (lithography, bonding, photomask)
- Hybrid Bonding
- Wafer Cleaning

# Investor Relations Information

## Contact

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## Financial Calendar 2024

- ✓ **March 27** – Annual Report 2023
- ✓ **May 8** – Q1 Report 2024
- ✓ **June 11** – Annual General Meeting 2024
- **August 7** – Half Year Report 2024
- **November 7** – Nine Months Report 2024